

Title (en)

Electronic device comprising organic thin film with high dielectric strength

Title (de)

Elektronisches Bauteil mit organischen Dünnsfilmelement mit hoher Durchschlagsfestigkeit

Title (fr)

Un dispositif électronique comportant un mince film organique à haute rigidité diélectrique

Publication

**EP 0702377 A3 19970618 (EN)**

Application

**EP 95306237 A 19950906**

Priority

JP 21252794 A 19940906

Abstract (en)

[origin: EP0702377A2] Disclosed is an electronic device which comprises an electric substrate and an organic thin film with a high dielectric strength, wherein the organic thin film is formed on the surface of the substrate, and consists of a fluorine containing polymer having a molecular structure whose main chains are oriented substantially at the right angle with respect to the substrate and has an insulation strength of at least  $1 \times 10^8$  V/m. <IMAGE>

IPC 1-7

**H01B 3/44**

IPC 8 full level

**H01B 3/44** (2006.01)

CPC (source: EP)

**H01B 3/44** (2013.01)

Citation (search report)

- [A] US 3684786 A 19720815 - CHANDRASEKARAN SWAYAMBU
- [A] EP 0444213 A1 19910904 - HITACHI LTD [JP]
- [A] PATENT ABSTRACTS OF JAPAN vol. 014, no. 188 (C - 0710) 17 April 1990 (1990-04-17)
- [A] PATENT ABSTRACTS OF JAPAN vol. 018, no. 573 (E - 1624) 2 November 1994 (1994-11-02)

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

**EP 0702377 A2 19960320; EP 0702377 A3 19970618**

DOCDB simple family (application)

**EP 95306237 A 19950906**